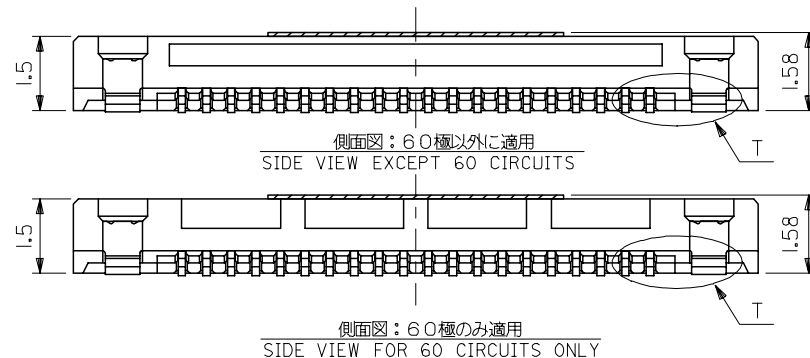
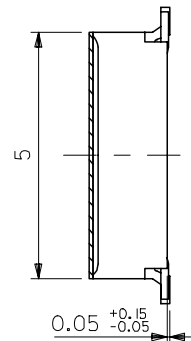
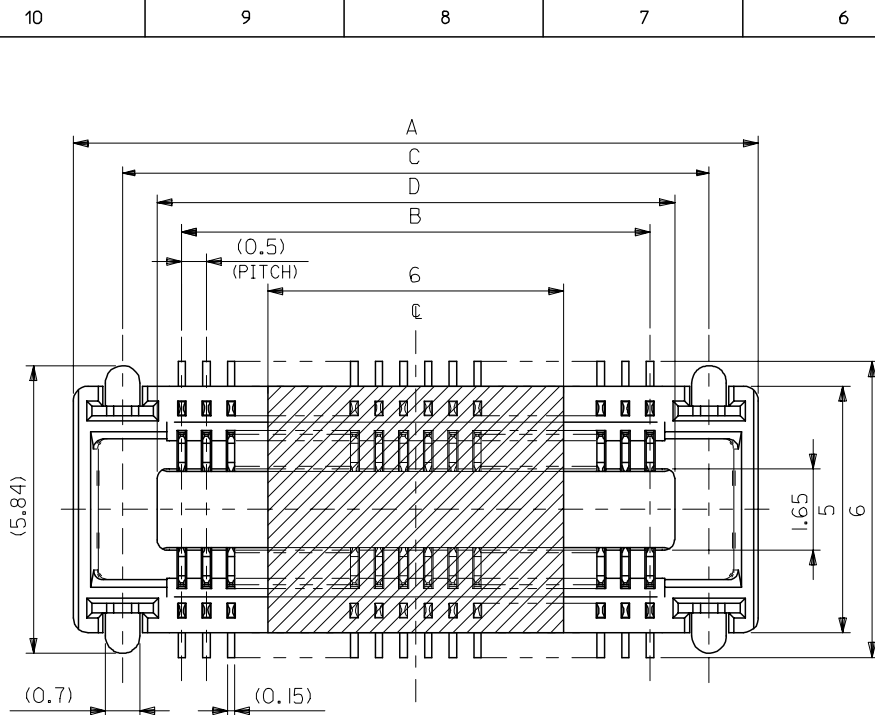


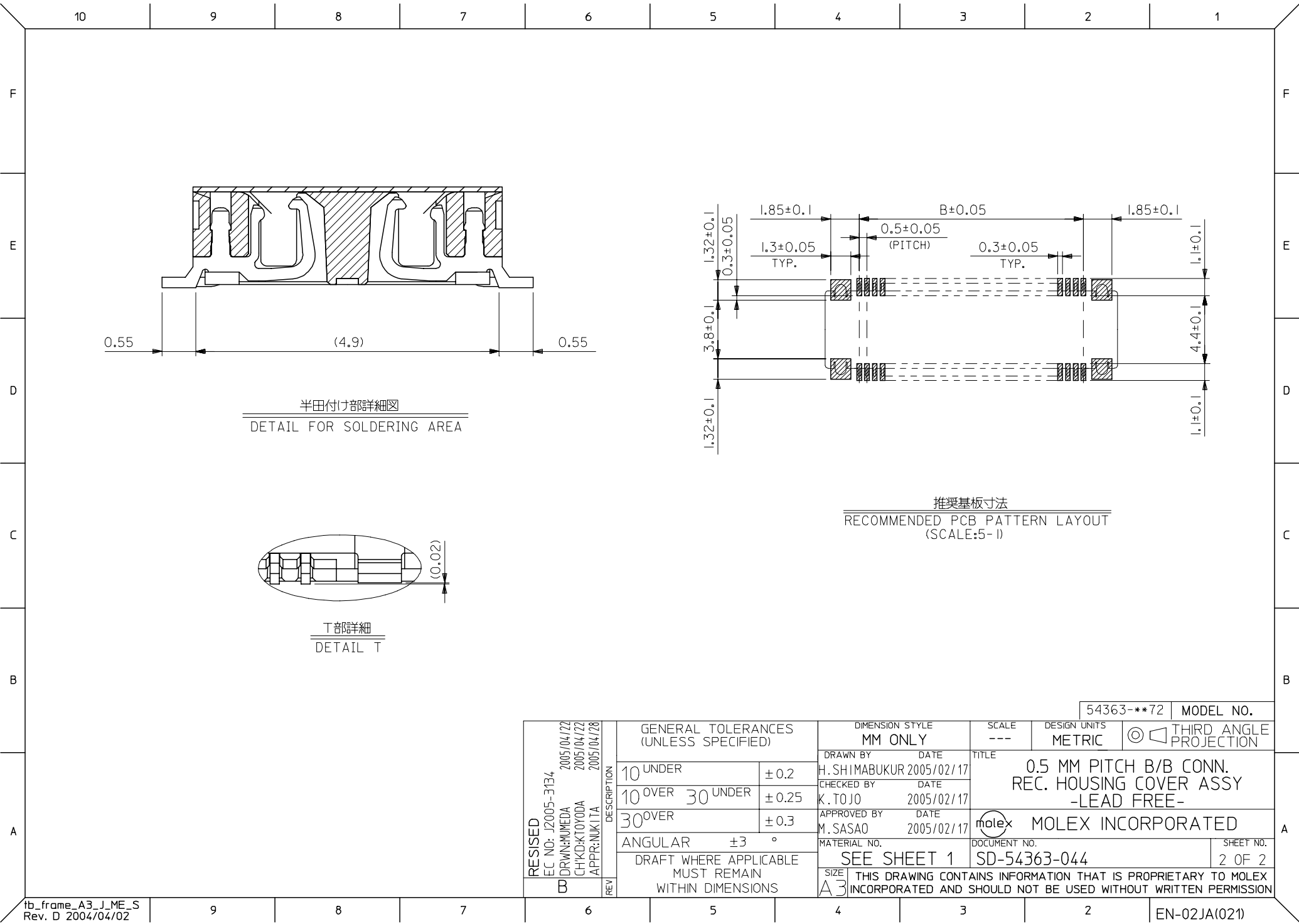


注記
NOTES:

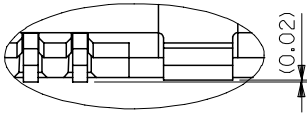
- 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.2)
NAIL: COPPER ALLOY (t=0.2)
カバーテープ: ポリイミド (t=0.08)
VACUUM TAPE: POLYIMIDE (t=0.08)
- メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM
半田付け部: 金メッキ 0.4マイクロメートル以下
SOLDER TAIL AREA: GOLD 0.4 MICROMETER MAXIMUM
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
ネイル
NAIL
錫メッキ 1.0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING: NICKEL PLATING 1.0 MICROMETER MINIMUM
- テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた
平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS
COPLANARITY TO BE 0.1 MAXIMUM.
- 嵌合相手: 55299 シリーズ (H=3mm)
: 55201 シリーズ (H=3mm) シリーズ (H=2mm)
MATED CONN.: 55299 SERIES (H=3mm)
: 55201, 55650 SERIES (H=2mm)
- 本製品は 54363-***2 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54363-****2

35.5	37.9	34.5	38.9	54363-1444	—//—	54363-1472	140	○
25.5	26.9	24.5	28.9	54363-1044	54363-0044	54363-1072	100	○
13	14.4	12	16.4	54363-0544	54363-5044	54363-0572	50	○
10.5	11.9	9.5	13.9	54363-0444	54363-4044	54363-0472	40	○
8	9.4	7	11.4	54363-0344	54363-3044	54363-0372	30	○
5.5	6.9	4.5	8.9	54363-0244	54363-2044	54363-0272	20	○
D	C	B	A	エンボス梱包品 EMBOSSED TAPE PACKAGING REEL DIA.=380MM	エンボス梱包品 EMBOSSED TAPE PACKAGING REEL DIA.=330MM	製品番号 MATERIAL NO. MODEL NO. 54363-**72	極数 CIRCUITS	量産対応 AVAILABLE

REVISED EC NO.: J2005-3134 DRAWN: MIMEDA CHKD: K. TOYODA APPR: NUKIITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		10:1	METRIC			
		10 UNDER	±0.2	DRAWN BY H. SHIMABUKUR	DATE 2004/02/17	TITLE 0.5 MM PITCH B/B CONN. REC. HOUSING COVER ASSY -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/02/17					
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/02/17	MOLEX MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-54363-044		1 OF 2		
REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



半田付け部詳細図
DETAIL FOR SOLDERING AREA



下部詳細
DETAIL T

推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE:5-1)

54363-***72 MODEL NO.

REVISED EC NO: J2005-3134 DRWN:MIMEDA 2005/04/22 CHKD:KTOYODA 2005/04/22 APPR:NUKITA 2005/04/28 B	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY H.SHIMABUKUR 2005/02/17		TITLE 0.5 MM PITCH B/B CONN. REC. HOUSING COVER ASSY -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K.TOJO 2005/02/17						
		30 OVER	±0.3	APPROVED BY M.SASAO 2005/02/17		MOLEX MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.			DOCUMENT NO.			SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1			SD-54363-044			2 OF 2
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

1

SD-54363045.SQ

